

# TI Designs – Precision: Verified Design

## Instrumentation Amplifier with DC Rejection Reference Design



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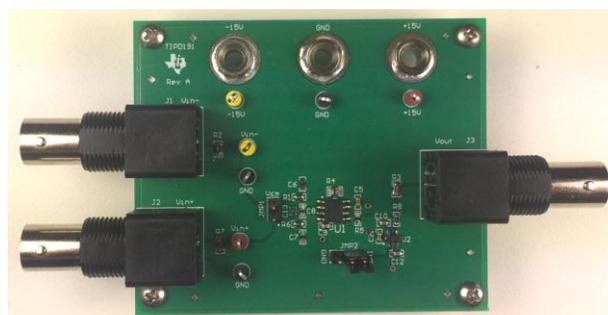
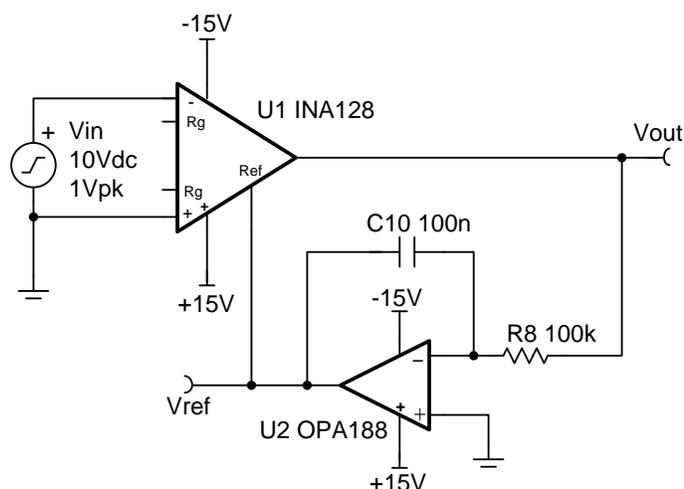
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### Circuit Description

This design is an ac coupled instrumentation amplifier. More specifically, the circuit amplifies ac differential input signals and rejects dc differential and common mode signals. The input is dc coupled, so it achieves effective ac coupling by shifting the instrumentation amplifier reference voltage to cancel output offset.



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## Design Summary

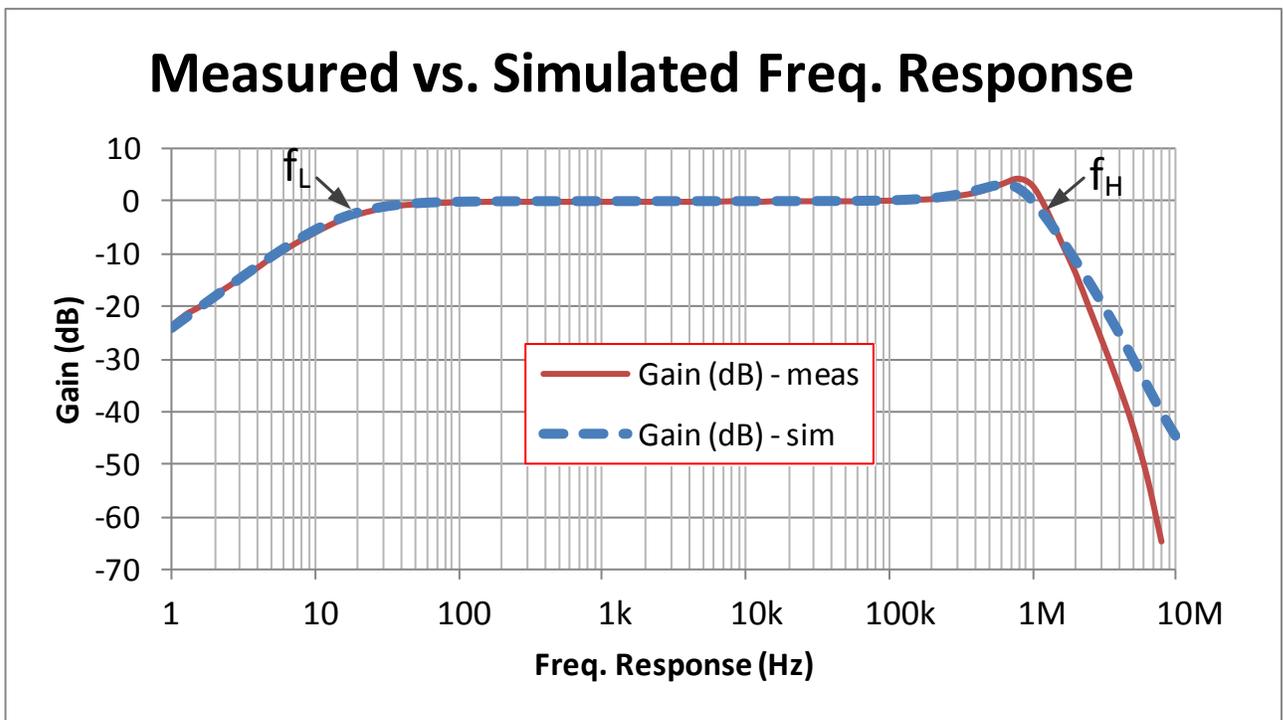
The design requirements are as follows:

- Supply Voltage:  $\pm 15\text{ V}$
- Input: small ac input with large dc offset (0 to 1Vpk with -10V to +10V dc offset).
- Output ac coupled

The design goals and performance are summarized in Table 1. Figure 1 depicts the measured and simulated ac transfer characteristic of the design.

**Table 1. Comparison of Design Goals, Simulation, and Measured Performance**

	Goal	Calculated	Simulated	Measured
$f_L$	16Hz	16Hz	16Hz	16Hz
$f_H$	1MHz	1.3MHz	1.12MHz	750kHz



**Figure 1: Simulated and Measured Transfer Function**

## 1 Theory of Operation

Figure 2 shows the schematic of the instrumentation amplifier with dc rejection. This TI Design behaves very similar to any ac coupled circuit in that the dc signal is rejected and the ac signal is passed. The ac transfer characteristic even looks the same as other ac coupled circuits as it has a lower cutoff frequency and a pass band. The main difference is that this circuit does not use large coupling capacitors on the input to ac couple the signal. Rather, the input is dc coupled and the output dc average is eliminated by integrating the output and subtracting the dc average using the reference pin. In section 6.1 we will cover some advantages of this method of ac coupling as compared to the capacitive input coupling method.

Notice in Figure 2 that the integrator (U2) is an inverting integrator. Also, remember that the integral of a sinusoidal wave is zero where as the integral of a dc constant is a ramp function. This circuit will cause the output of U2 to servo to a dc constant voltage that will cancel the output dc offset voltage on this circuit. You can think of the integrator as a low pass filter that translates the instrumentation amplifier into a high pass by canceling the dc and low frequency components on the circuit's output (see reference 2).

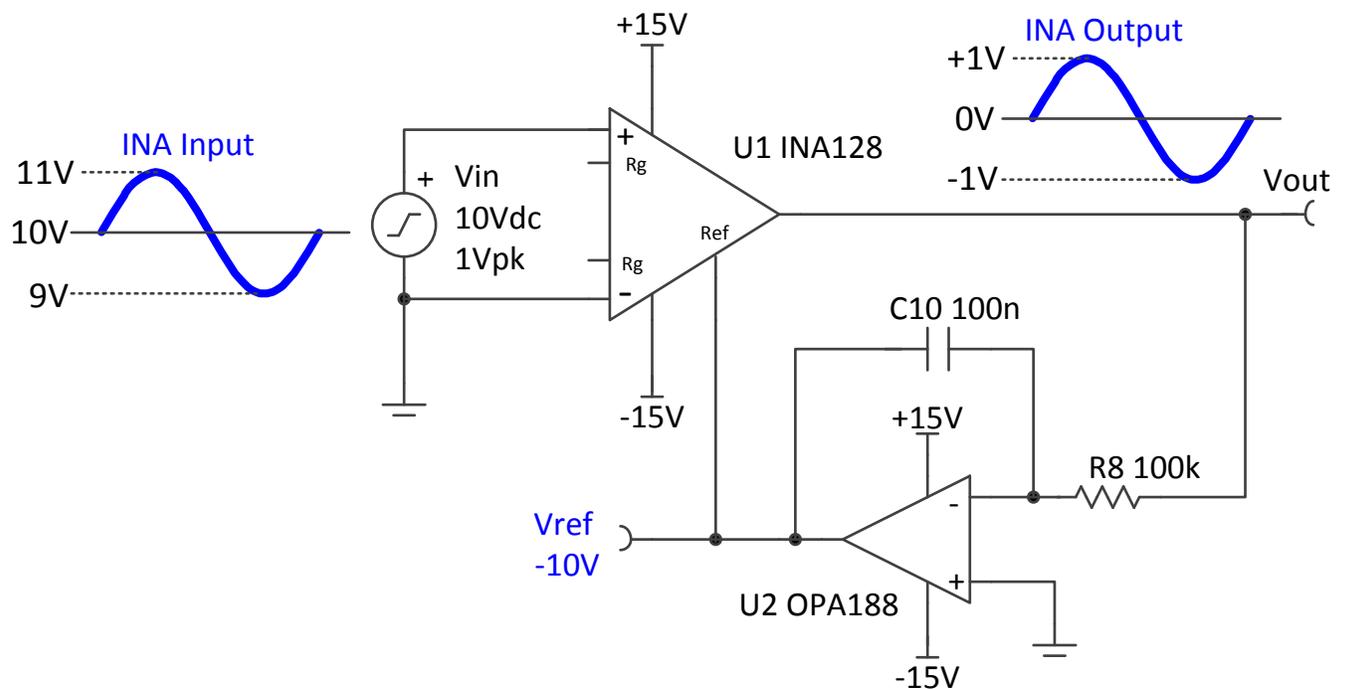


Figure 2: Single Supply ac Coupled Amplifier

## 1.1 Setting ac Response – Cutoff Frequencies

The input RC network  $R_8$  and  $C_{10}$  set the lower cutoff frequency for the circuit. Equation ( 1 ) gives the general relationship for the lower cutoff frequency. In this example the cutoff is set to 16Hz. For most applications it is desirable to set  $f_L$  as low as possible. Increasing  $R_8$  or  $C_{10}$  will decrease this frequency further, but this will also increase the transient startup for this circuit.

$$f_L = \frac{1}{2\pi R_8 C_{10}} \frac{1}{2\pi(100k\Omega)(100nF)} = 16\text{Hz} \quad (1)$$

The upper cutoff frequency is set by the bandwidth of the instrumentation amplifier (U1). The data sheet for the INA128 specification table provides bandwidth information for different closed loop gains (in this case  $f_H = 1.3\text{MHz}$ ). Figure 3 shows the position of the upper and lower cutoff frequency on the frequency response curve.

$$f_H = 1.3\text{MHz} \quad (2)$$

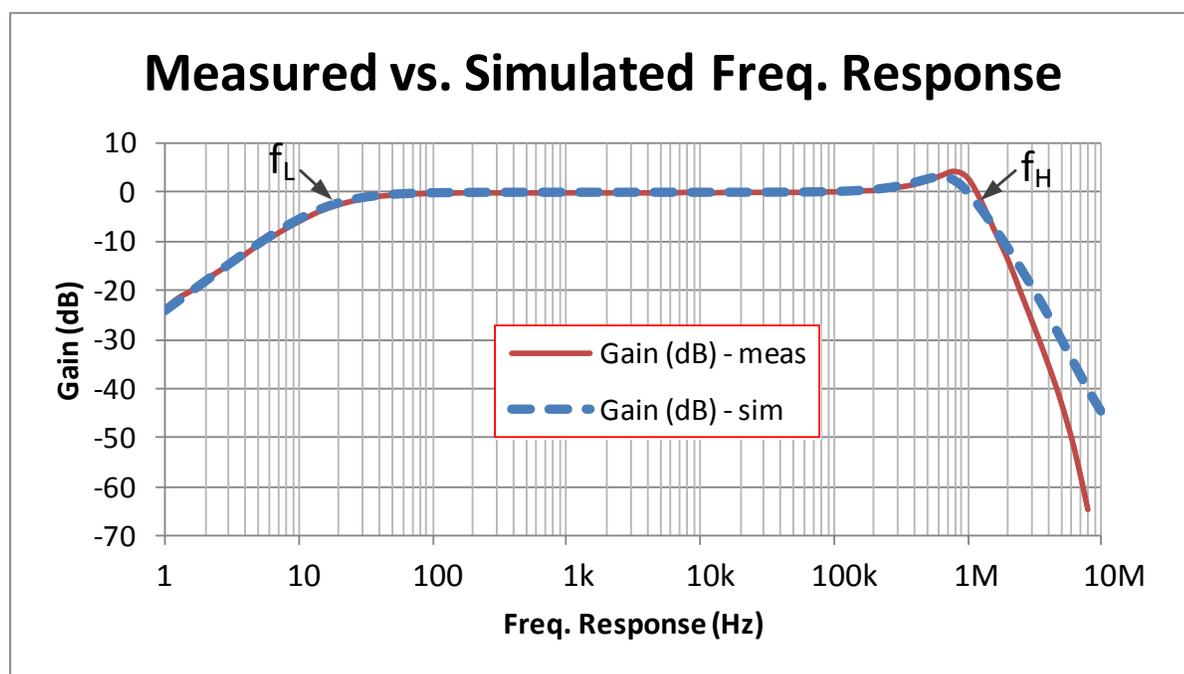


Figure 3: Lower and upper cutoff frequency shown on ac transfer characteristic

## 2 Component Selection

### 2.1 *Op Amp and Instrumentation Amplifier*

The OPA188 was selected for its dc precision. Any offset on the OPA188 will directly appear as an error source on the output. The INA128 was selected for its excellent gain accuracy, low gain drift, low noise, and common mode rejection. This device also has very good dc accuracy, but that is not required in this application as the circuit is ac coupled.

### 2.2 *Passive Components*

This design uses 1% thin film resistors and X7R ceramic capacitors. Special low distortion capacitors (C0G) are not practical as a large capacitance value is normally needed for  $C_{10}$ . It is recommended to choose a best voltage coefficient possible for this capacitor type to minimize shifting  $C_{10}$  verses dc voltage. Shifting of  $C_{10}$  will cause shifting of the lower cutoff frequency. Note that for a fixed voltage level, capacitors with higher voltage ratings are generally less sensitive to changes in dc voltage. For example, for a 10Vdc applied voltage, a capacitor with a 50V rating is less sensitive than a capacitor with a 25V rating. For this reason,  $C_{10}$  was selected with a 50V rating. Also, a “soft termination” type capacitor was used as this is less sensitive to microphonics (variations in capacitance due to vibration).

### 3 Simulation

#### 3.1 Transfer Function

The simulated and measured response vs frequency is shown in Figure 4. As mentioned in section 1.1, the lower cutoff frequency is set by input coupling capacitor C10 and input resistor R8. The upper cutoff frequency is set by the instrumentation amplifiers bandwidth limitation. The simulation and measurement results for both the upper and lower cutoff frequencies match well.

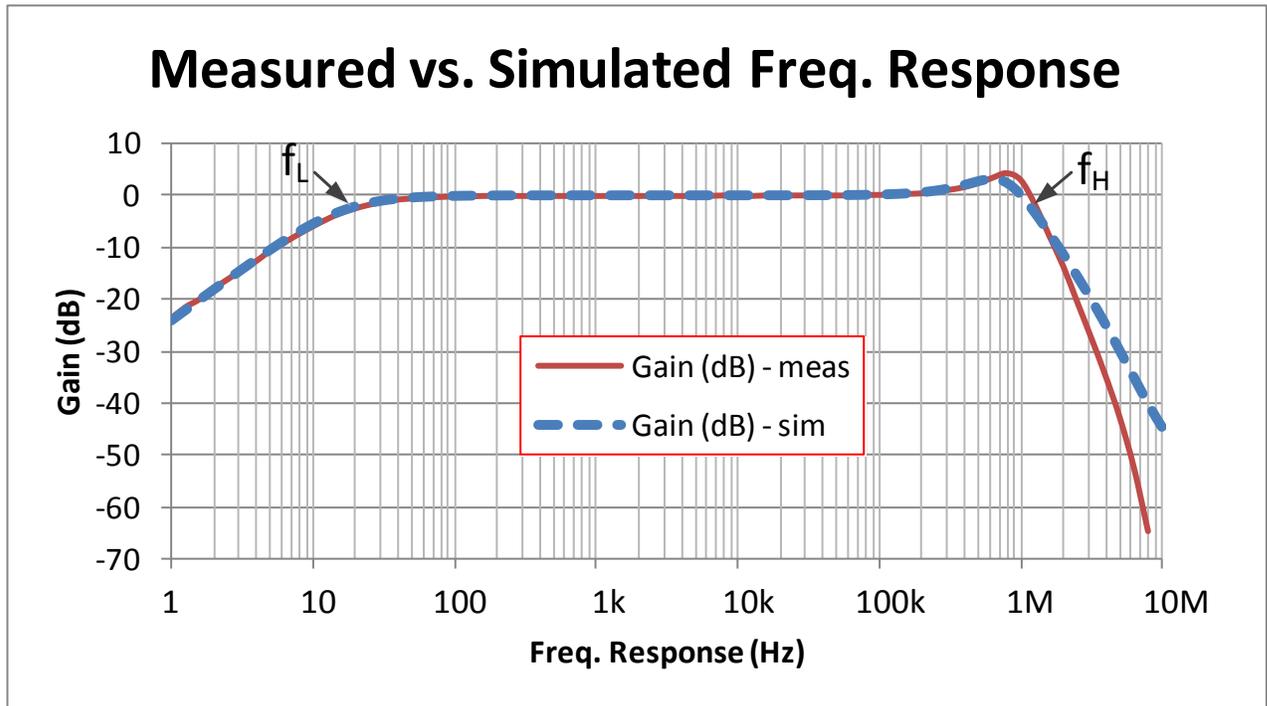
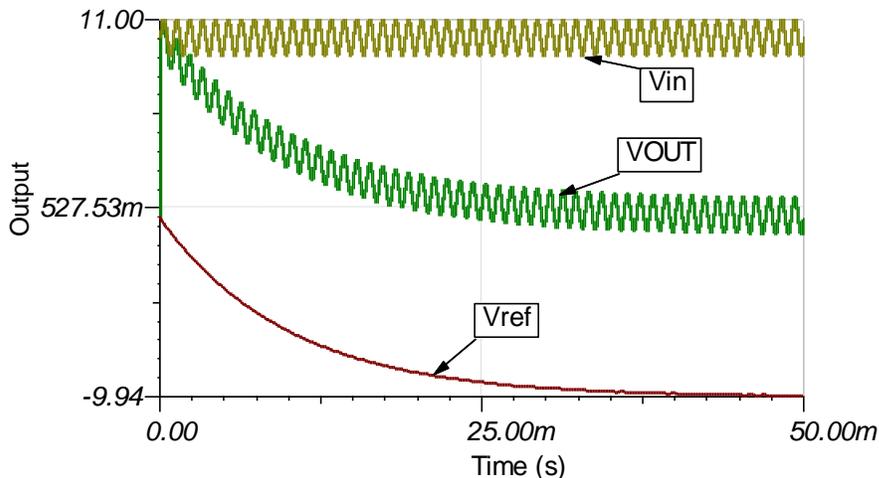


Figure 4: Frequency response for INA118 and OPA188 dc rejection circuit

### 3.2 Transient – Startup

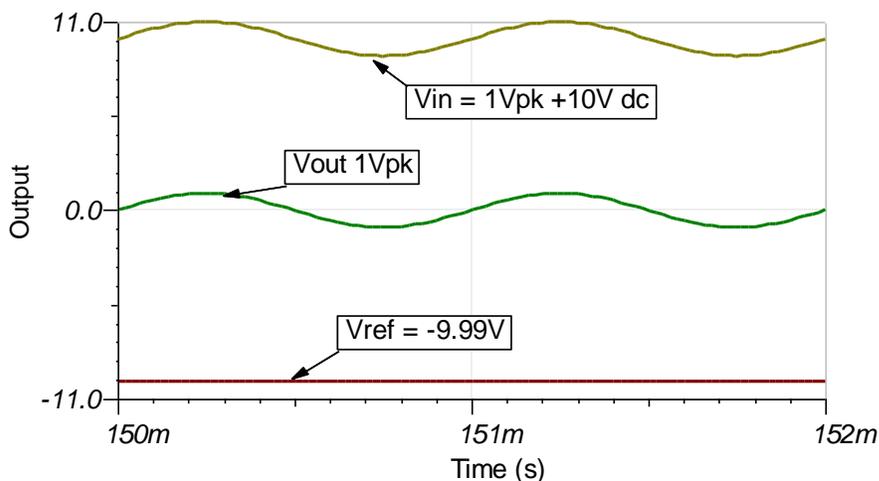
The simulation below shows the startup condition with the input source set to 1Vpk @1kHz +10Vdc. Notice that the output of the integrator ramps to cancel the dc offset on the ac signal. After the initial startup transient, the output will track the ac signal and reject the dc offset.



**Figure 5: Startup Transient Integrator Ramping to Cancel Output Offset**

### 3.3 Transient – Steady State

The simulation below shows the steady state response for 1Vpk @ 1kHz +10Vdc signal.



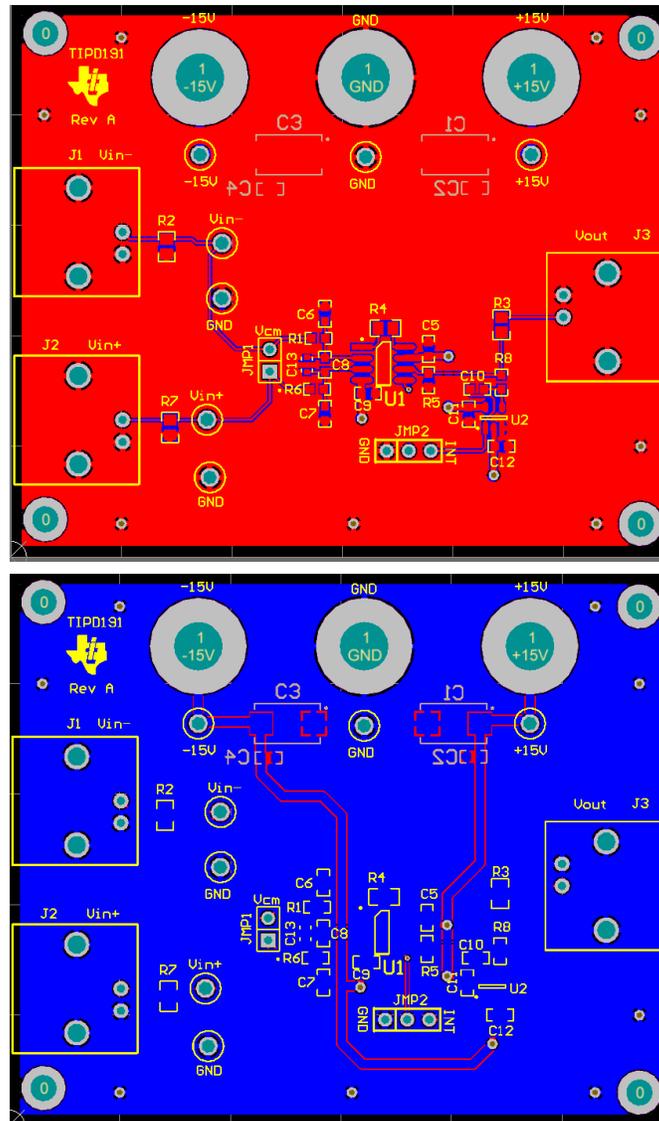
**Figure 6: Steady State Transient to 1Vpk+10Vdc 1kHz Input Signal**

## 4 PCB Design

Note that this PCB includes both the inverting and non-inverting ac coupled amplifier. The PCB schematic and bill of materials can be found in the Appendix.

### 4.1 PCB Layout

Normal PCB layout precautions were in this layout (i.e. short traces, solid ground connections, minimized vias, close decoupling capacitors).



**Figure 7: PCB Layout (Top - Red, Bottom - Blue)**

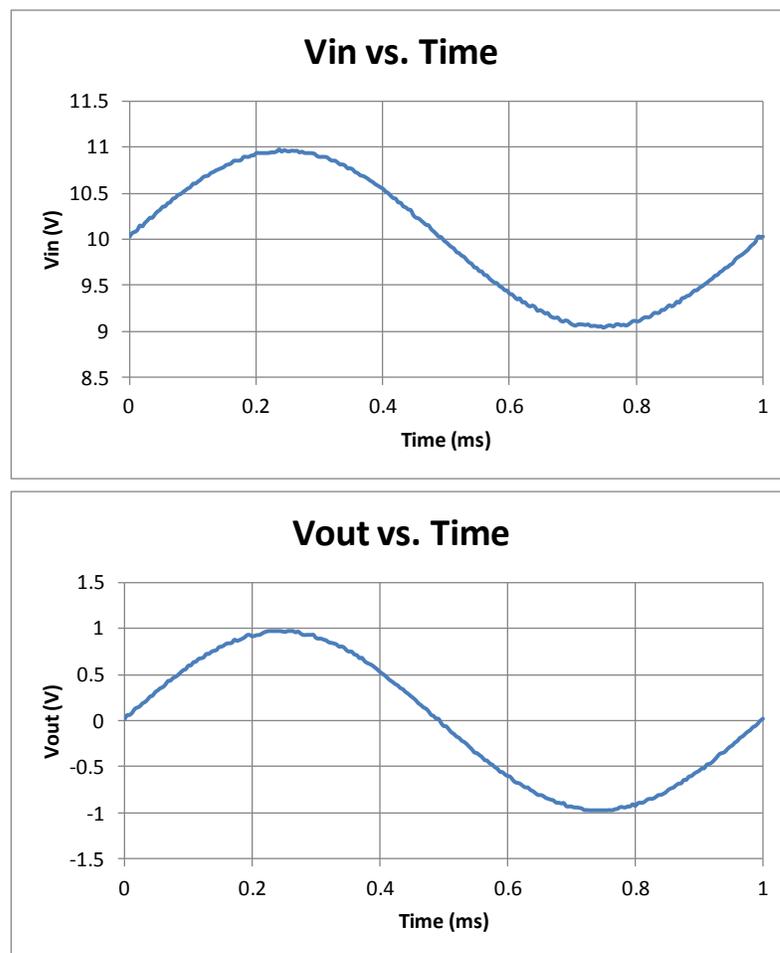
## 5 Verification & Measured Performance

### 5.1 Transfer Function

The measured and simulated ac transfer function is compared to each other in section 3.1. The measured results compare well with the simulations.

### 5.2 Transient – Steady State

Figure 8 shows the steady state response to a 1Vpk @ 1kHz +10Vdc sinusoidal waveform. The input is multiplied by a gain of one and the dc offset is eliminated. Thus, the output signal is 1Vpk @ 1kHz ac signal with no offset.



**Figure 8: Transient Response to a 1Vpk 1kHz + 10Vdc Input Signal**

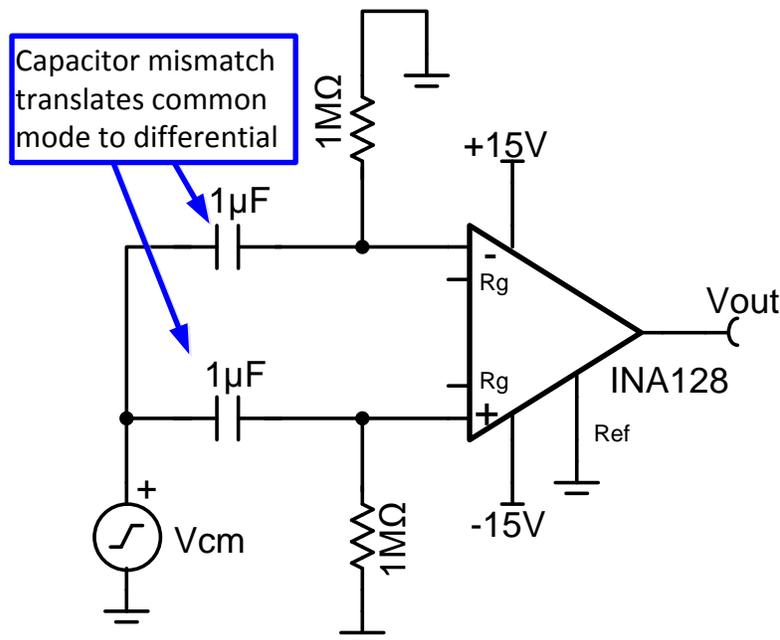
## 6 Modifications

Depending on your design goal you may choose different values.

Design Goal	Modification	Trade off										
Lower low cutoff frequency	Increase R1 x C1	This will increase transient start up time.										
Upper cutoff frequency	Choose an instrumentation amplifier with wider bandwidth	Wider bandwidth devices normally draw more current.										
Gain	<p>Select a value of the gain setting resistor (R4 on the schematic in Appendix A.1).</p> $\text{Gain} = \frac{50\text{k}\Omega}{R_4} + 1$	<p>The amount of dc offset that be corrected is impacted by the gain. Large gain, means that less dc offset correction is achievable. As a good estimate for dc correction, the dc correction range by the gain for higher gains.</p> <table> <thead> <tr> <th>Gain</th> <th>dc correction range</th> </tr> </thead> <tbody> <tr> <td>1V/V</td> <td>±10Vdc</td> </tr> <tr> <td>10V/V</td> <td>±1Vdc</td> </tr> <tr> <td>100V/V</td> <td>±0.1Vdc</td> </tr> <tr> <td>1000V/V</td> <td>±0.01Vdc</td> </tr> </tbody> </table>	Gain	dc correction range	1V/V	±10Vdc	10V/V	±1Vdc	100V/V	±0.1Vdc	1000V/V	±0.01Vdc
Gain	dc correction range											
1V/V	±10Vdc											
10V/V	±1Vdc											
100V/V	±0.1Vdc											
1000V/V	±0.01Vdc											

### 6.1 Alternative Implementation – Some Tradeoffs

Another ac coupled instrumentation amplifier implementation is shown in Figure 9. This circuit only requires two input coupling capacitors and two input resistors (1 $\mu$ F and 1M $\Omega$  in this example). Because of its simplicity, one may initially choose this implementation; however, it has a significant disadvantage over the approach covered in this TI Design. The key disadvantage to circuit shown in Figure 9 is that it translates common mode signals into differential signals. Note that the input capacitors have a tolerance between 1% and 10%, so the mismatch can be significant. This mismatch will effectively translate low frequency common mode signals into low frequency differential signals. One example where this can be especially problematic is ECG signals. In this case the common mode noise (e.g. 60Hz power line pick-up) is in the same frequency range as the measured signal. In this example it is very important that the low frequency common mode signal is rejected. The circuit from this TI Design (Figure 2) has a dc coupled input so that it does not translate common mode signals to differential signals. The circuit shown in Figure 9, on the other hand, will translate common mode noise to differential noise.



**Figure 9: ac Coupled with Input Capacitors Error Source - Common Mode to Differential Translation**

## 7 About the Author

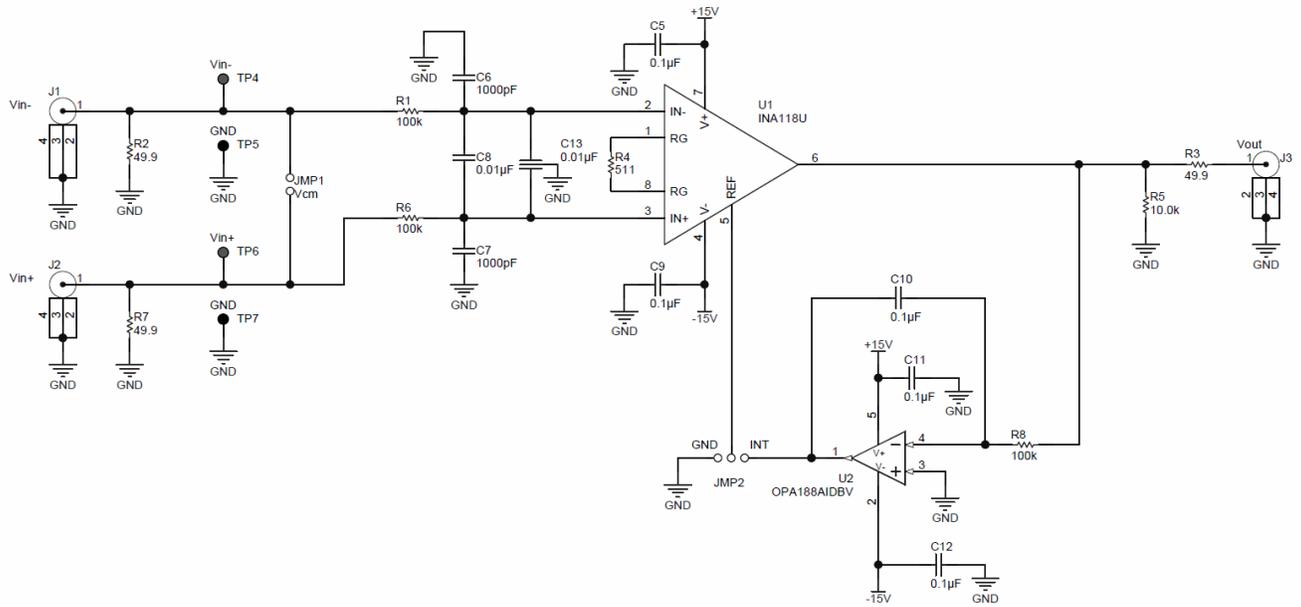
Arthur Kay is an applications engineering manager at TI where he specializes in the support of amplifiers, references, and mixed signal devices. Arthur focuses a good deal on industrial applications such as bridge sensor signal conditioning. Arthur has published a book and an article series on amplifier noise. Arthur received his M.S.E.E. from Georgia Institute of Technology, and B.S.E.E. from Cleveland State University.

## 8 Acknowledgements & References

1. *M. Hann. (2011). SIGNAL CHAIN BASICS #58: Analyze the RL drive in an ECG front end using SPICE. Available: [http://www.planetanalog.com/document.asp?doc\\_id=528240](http://www.planetanalog.com/document.asp?doc_id=528240)*
2. *R. Mark Stitt. (1990, Oct 10). SBOA003: AB-008A – AC Coupling Instrumentation and Difference Amplifiers Available: <http://www.ti.com/litv/pdf/sboa003>*

## Appendix A.

### A.1 Electrical Schematic



**Figure A-1: Electrical Schematic**

Note: the schematic allows for many options that are not used in this TI Design. In some cases components may not be installed, or may have a value different than what is shown in the schematic. Refer, to the bill of material for component values.

## A.2 Bill of Materials

Qty	Designator	Description	Manufacture	Part Number	Supplier Part Number
2	C1, C3	CAP, TA, 10 $\mu$ F, 50 V, +/- 10%, 0.8 ohm, SMD	Vishay Sprague	293D106X9050E2TE3	718-1022-1-ND
7	C2, C4, C5, C9, C10, C11, C12	CAP, CERM, 0.1 $\mu$ F, 25 V, +/- 10%, X5R, 0603	AVX Corporation	06033D104KAT2A	478-1244-1-ND
1	C10	CAP CER 0.1UF 50V 5% X7R 0603	AVX Corporation	06035C104J4Z2A	478-7426-1-ND
2	C6, C7	DO NOT INSTALL			
1	C8	DO NOT INSTALL			
1	C13	DO NOT INSTALL			
1	J1, J2, J3	CONN BNC JACK R/A 50 OHM PCB	TE Connectivity	1-1634612-0	A97555-ND
1	J4, J5, J6	JACK NON-INSULATED .218", Banana Jack	Keystone Electronics	575-4	575-4K-ND
2	JMP1, JMP2	SHUNT LP W/HANDLE 2 POS 30AU	TE Connectivity	JUMP3	A26242-ND
1	JMP1, JMP2	CONN HEADER 50POS .100" SGL GOLD	Samtec Inc	JUMP3	SAM1029-50-ND
2	R1, R6	RES SMD 0.0 OHM JUMPER 1/10W	Panasonic Electronic Components	ERJ-3GEY0R00V	P0.0GCT-ND
3	R2, R3, R7, R8	DO NOT INSTALL			
1	R4	DO NOT INSTALL			
1	R5	DO NOT INSTALL			
1	R8	RES, 100 k, 0.1%, 0.063 W, 0603	TE Connectivity	CPF0603B100KE	A119912CT-ND
1	TP1, TP4, TP6	Test Point, TH, Compact, Red	Keystone Electronics	5005	5005K-ND
3	TP2, TP5, TP7	Test Point, TH, Compact, Black	Keystone Electronics	5006	5006K-ND
1	TP3	Test Point, TH, Compact, Yellow	Keystone Electronics	5009	5009K-ND
1	U1	Precision, Low Power INSTRUMENTATION AMPLIFIER, SOIC-8	Texas Instruments	INA118U	296-26056-1-ND
1	U2	Precision, Low-Noise, Rail-to-Rail Output, 36-V, Zero-Drift Operational Amplifier, SOT23-5	Texas Instruments	OPA188AIDBV	296-36218-1-ND
4		STANDOFF HEX 4-40THR ALUM 1L"	Keystone Electronics	2205	2205K-ND
4		MACHINE SCREW PAN PHILLIPS 4-40	B&F Fastener Supply	PMSSS 440 0025 PH	H703-ND

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